

REMARKS

35 U.S.C. § 103 Rejections

The Examiner has rejected claims 1, 5-8, and 12-14 under 35 U.S.C. § 103(a) as being unpatentable over Murayama in view of Brodsky. Specifically, the Examiner states as follows:

"Regarding claim 5, Murayama discloses in Fig. 6 the die is rounded at the corner edge portion, wherein an entire thickness from the upper to the lower major surface is rounded."

Referring to Figure 6 of Murayama, it can clearly be seen that the edges at D are flat, giving the die an eight-sided profile. The corners at D are thus not rounded. Murayama also states in Paragraph 0039 as follows:

"There is a contour of a semiconductor chip 12 or a substrate 10 as shown in Fig. 6 wherein corners thereof are cut off. In such a semiconductor chip 12 or substrate 10, an imaginary corner D is conveniently defined by an intersection between extensions of the respective sides, and a diagonal line is defined by a straight line connecting these imaginary corners D with each other."

There is thus no suggestion in Murayama that the corners can be profiled in any other manner than by cutting them off in "a straight line."

What should also be noted is that Murayama fails to disclose any tool or device that can be used to form rounded corners from top to bottom.

Referring now to Brodsky in, for example, Fig. 2, a domed upper surface 64 is provided (see column 3, line 49). Fig. 8 illustrates how the domed upper surface is formed. A wheel 120 having a concave cutting surface 122 is used to cut into a flat upper surface 73 and the cutting surface 122 has a shape that

defines the domed shape of domed the upper surface 64 (see column 4, lines 9-21). Brodsky does not disclose any tool or device that can be used for rounding the corners 110 from the flat upper surface 73 to the bottom surface 59. In fact, in the embodiment of Fig. 7 of Brodsky, it can be seen that the corner edge surface cannot even be accessed when the upper surfaces 64 are domed.

Both Murayama and Brodsky thus fail to disclose any tool or device that can be used for rounding corners from an upper surface to a lower surface. Claim 1 now specifically includes the limitation that the entire thickness of the die from the upper to the lower surface is rounded. Claim 1 thus includes at least one limitation that is not suggested by Murayama or Brodsky, alone or in combination.

Applicant, accordingly, respectfully submits that claim 1 is patentable over Murayama and Brodsky. Claims 2, 3, 6, and 7 depend from claim 1 and should be allowable for at least the same reasons as claim 1. Claim 8 has been amended to include limitations similar to the limitations that have been added to claim 1 and should be allowable for at least the same reasons as claim 1. Claims 9 and 1--14 depend from claim 8 and should be allowable for at least the same reasons as claim 8.

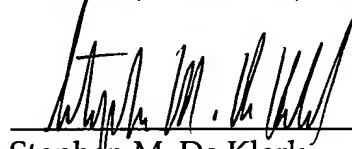
Applicant, accordingly, respectfully requests withdrawal of the rejections under 35 U.S.C. § 103(a) of claims 1, 2, 4, 6-9, and 11-14 in view of Murayama and Brodsky.

Applicant respectfully submits that the present application is in condition for allowance. If the Examiner believes a telephone conference would expedite or assist in the allowance of the present application, the Examiner is invited to call Stephen M. De Klerk at (408) 720-8300.

Please charge any shortages and credit any overages to Deposit Account No. 02-2666. Any necessary extension of time for response not already requested is hereby requested. Please charge any corresponding fee to Deposit Account No. 02-2666.

Respectfully submitted,

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